

KYOCERA KE-850SH

Epoxy; Epoxide

KYOCERA Chemical Corporation

Message:

Developed for Power Device Package that needs Good Heat Dissipation Through Molding Compound.

Strong Points

High Thermal Conductivity with Good Moldability, Excellent Moisture Resistance and Low Stress.

Used in Auto Molding System by Rapid Cure Grades.

KE-870 and KE-880 is Formulated with Special High Thermal Conductivity Filler System and Achieve High Thermal Conductivity (above 3W/m K).

Application

Isolation Packages such as TO-220 and TO-3P that need Heat Dissipation Characteristics.

Packages for High Heating Volume such as Power Module.

General Information		
Features	Good Moldability	
	Moisture Resistant	
	Thermally Conductive	
Uses	Electrical/Electronic Applications	
Physical	Nominal Value	Unit
Specific Gravity	2.19	g/cm ³
Spiral Flow	35.0	cm
Thermal	Nominal Value	Unit
Glass Transition Temperature	175	°C
CLTE - Flow		
-- ¹	2.2E-5	cm/cm/°C
-- ²	5.9E-5	cm/cm/°C
Thermal Conductivity	2.3	W/m/K
Uncured Properties	Nominal Value	Unit
Gel Time	0.42	min
NOTE		
1.	Alpha 1	
2.	Alpha 2	

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